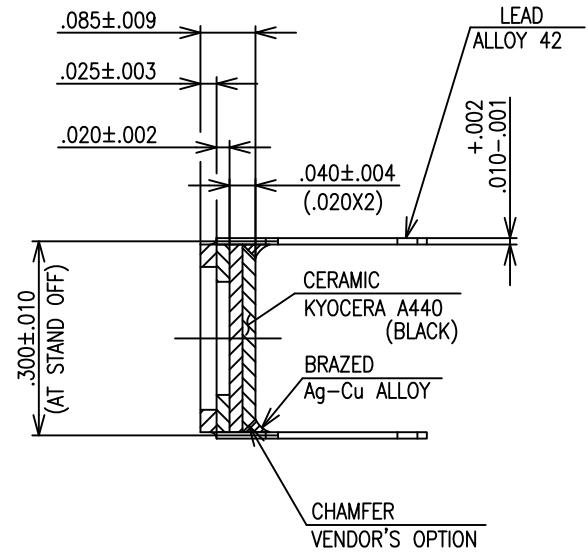
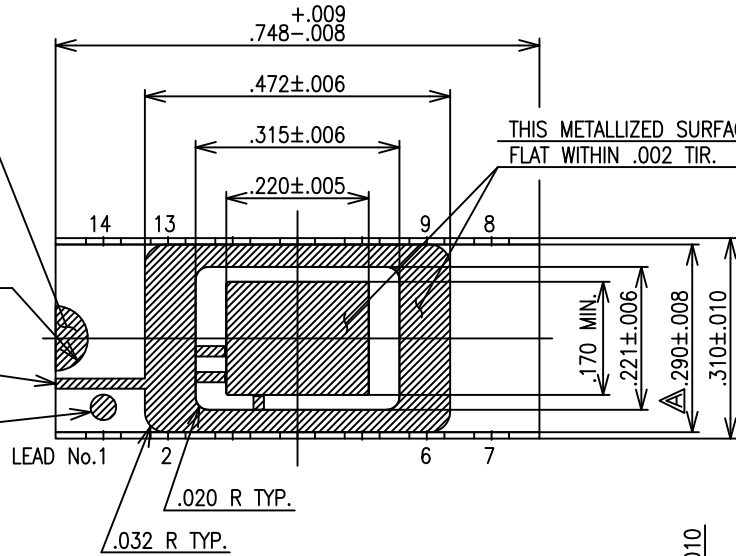


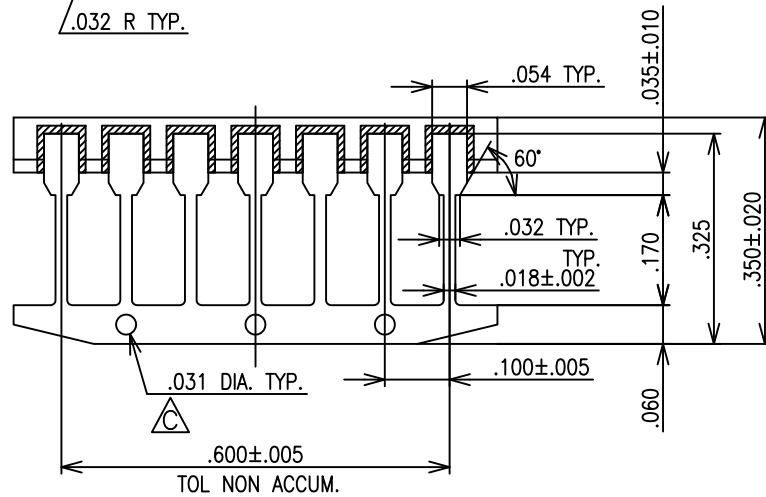
# SSM P/N: CSB01440

THIS METALLIZED AREA IS CONNECTED TO DIE ATTACH PAD (ONLY PART No.01)

THIS METALLIZED SURFACE TO BE FLAT WITHIN .002 TIR.



PART No.	NOTCH AREA METALLIZED
01	WITH METALLIZATION
02	WITHOUT METALLIZATION



**NOTES:**

1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
2. LEAD RESISTANCE : 0.2 OHM MAX.
3. SEAL AREA TO BE METALLIZED.
4. DIE ATTACH AREA TO BE METALLIZED.
5. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
6. WIRE BOND PAD CONNECTED TO CORRESPONDED OUTER LEADS.
7. MISALIGNMENT OF METALLIZATION PATTERN IN CAVITY SHALL BE ACCEPTED DUE TO LAYER MISALIGNMENT.

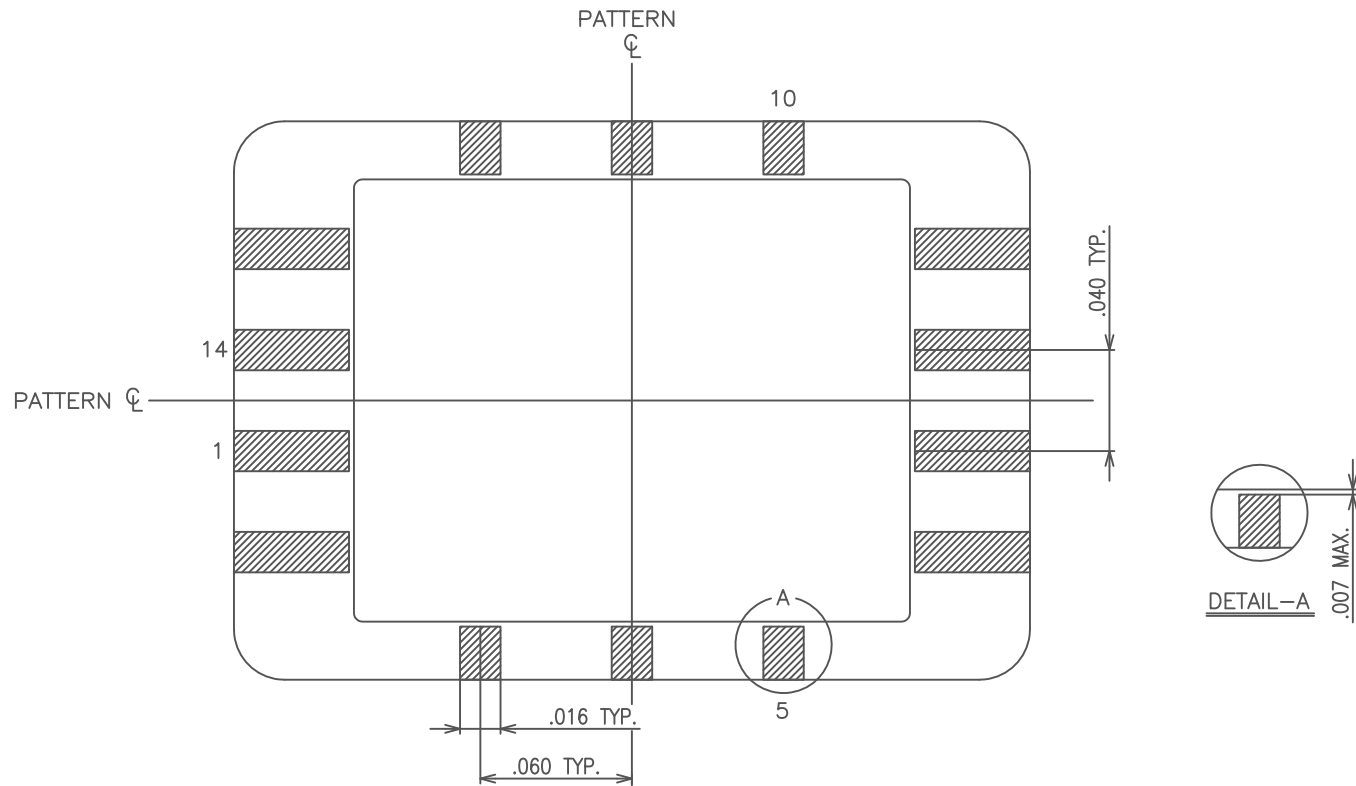
SB014M528-2	S=0 D=0
SB014M528-1	S=0 D=0

MODIFICATION	DESCRIPTION	DATE	DRAWN	CHECKED	APPROVED
⊠	ADDED : PART No.2 , NOTE 6,7 , DELETED : VENDOR'S OPTION.	JUN.19.'08	Y.H	TO.H./M.SU	S.NI
⊠	CONVERTED CAD DATA , ADDED SHEET 2/2	JAN.31.'00	T.K	H.TA	H.SA
⊠	CHANGED : .225 → .221	AUG.9.'82	T.H	K.M	
	CHANGED	DATE	DRAWN	CHECKED	APPROVED

NAME	14 LEAD SIDE BRAZED PACKAGE	TOLERANCE	UNLESS OTHERWISE SPECIFIED	±.005	THIRD ANGLE PROJECTION
SCALE	5 / 1	MATERIAL	AS INDICATED		
			KYOCERA CORPORATION KYOTO JAPAN		DRAWING NO. KD-S82528-C
					SHEET 1 / 2



# SSM P/N: CSB01440



BONDING PATTERN

MODIFICATION						NAME	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
						14 LEAD SIDE BRAZED PACKAGE	UNLESS OTHERWISE SPECIFIED	T.H	K.M		JUL.29.'82
						SCALE 20 / 1	MATERIAL				
							THIRD ANGLE PROJECTION				
	CHANGED	DATE	DRAWN	CHECKED	APPROVED	KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO.	KD-S82528-C		SHEET	2 / 2



